

APPARATUS AND METHOD FOR TEMPERATURE CONTROL OF INTEGRATED CIRCUITS

ABSTRACT OF THE DISCLOSURE

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One embodiment disclosed relates to an apparatus for temperature control of an integrated circuit on a circuit board. The apparatus includes a first resistor on the circuit board, a second resistor on the circuit board, and a heat conductive material. The heat conductive material is attached to both the first and second resistors and to a surface of a package containing the integrated circuit. Another embodiment disclosed relates to an apparatus that provides both cooling and heating functionality in order to maintain the operational temperature of the IC within an acceptable range.

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